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- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

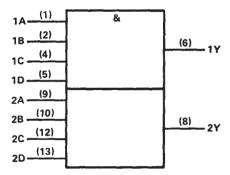
These devices contain two independent 4-input AND gates.

The SN54LS21 is characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN74LS21 is characterized for operation from 0 °C to 70 °C.

FUNCTION	TABLE	(each	gate)
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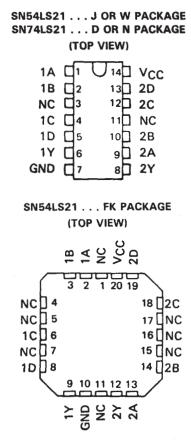
	INP	UTS	OUTPUT	
A	в	С	Y	
н	н	н	н	н
L	х	х	×	L
X	L	х	X	L
X	х	L	X	L
X	х	х	L	L

logic symbol[†]



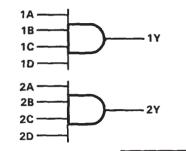
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



NC-No internal connection

logic diagram



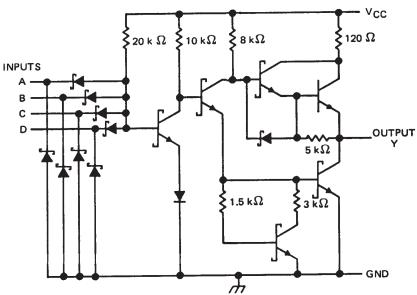
(positive logic) Y = A•B•C•D or Y = $\overline{\overline{A} + \overline{B} + \overline{C} + \overline{D}}$

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN54LS21, SN74LS21 DUAL 4-INPUT POSITIVE-AND GATES

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schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74' Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.



SN54LS21, SN74LS21 DUAL 4-INPUT POSITIVE-AND GATES

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recommended operating conditions

		SN54LS21		SN74LS21			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	v
VIH High-level input voltage	2			2			V
VIL Low-level input voltage			0.7			0.8	V
OH High-level output current			- 0.4			- 0.4	mA
IOL Low-level output current			4			8	mA
T _A Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	.			SN54LS21			SN74LS21			
PARAMETER		TEST CONDITIONS T		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	l _l = – 18 mA				- 1.5			1.5	V
VOH	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OH} ≂ – 0.4 mA	2.5	3.4		2.7	3.4		v
	V _{CC} = MIN,	VIL = MAX,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	v
VOL	V _{CC} = MIN,	VIL = MAX,	I _{OL} = 8 mA					0.35	0.5	
1	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
Чн	V _{CC} = MAX,	V _I = 2.7 V				20			20	μA
	V _{CC} = MAX,	V _I = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX,	V ₁ = 4.5 V			1.2	2.4		1.2	2.4	mA
ICCL	V _{CC} = MAX,	V _I = 0 V			2.2	4.4		2.2	4.4	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 \ddagger All typical values are at V_{CC} = 5 V, T_A = 25^oC § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
^t PLH		×	B. = 2 k0	C _L = 15 pF		8	15	ns
tPHL	Алу	Ť	$R_{L} = 2 k\Omega,$	0E - 19 bi		10	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/31003B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/31003BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/31003BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN54LS21J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN74LS21D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74LS21DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74LS21N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS21N3	OBSOLETE	PDIP	Ν	14		None	Call TI	Call TI
SN74LS21NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SNJ54LS21FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS21J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54LS21W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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